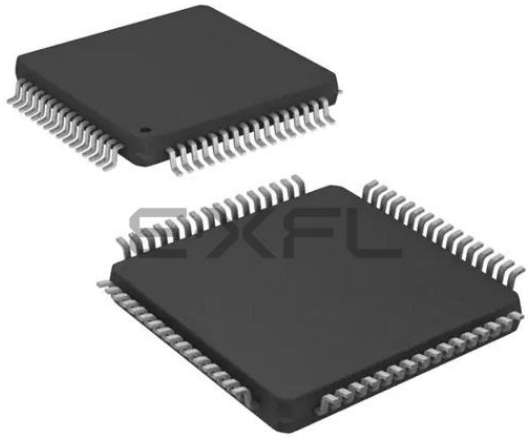

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	25MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	96KB (48K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f6627-e-pt

TABLE 1-3: PIC18F6527/6622/6627/6722 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTE is a bidirectional I/O port.
RE0/$\overline{RD}$/P2D	2			
RE0		I/O	ST	Digital I/O.
$\overline{RD}$		I	TTL	Read control for Parallel Slave Port.
P2D		O	—	ECCP2 PWM output D.
RE1/$\overline{WR}$/P2C	1			
RE1		I/O	ST	Digital I/O.
$\overline{WR}$		I	TTL	Write control for Parallel Slave Port.
P2C		O	—	ECCP2 PWM output C.
RE2/$\overline{CS}$/P2B	64			
RE2		I/O	ST	Digital I/O.
$\overline{CS}$		I	TTL	Chip select control for Parallel Slave Port.
P2B		O	—	ECCP2 PWM output B.
RE3/P3C	63			
RE3		I/O	ST	Digital I/O.
P3C		O	—	ECCP3 PWM output C.
RE4/P3B	62			
RE4		I/O	ST	Digital I/O.
P3B		O	—	ECCP3 PWM output B.
RE5/P1C	61			
RE5		I/O	ST	Digital I/O.
P1C		O	—	ECCP1 PWM output C.
RE6/P1B	60			
RE6		I/O	ST	Digital I/O.
P1B		O	—	ECCP1 PWM output B.
RE7/ECCP2/P2A	59			
RE7		I/O	ST	Digital I/O.
ECCP2**(2)**		I/O	ST	Enhanced Capture 2 input/Compare 2 output/ PWM 2 output.
P2A**(2)**		O	—	ECCP2 PWM output A.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels Analog = Analog input
I = Input O = Output
P = Power I^2C™ = I^2C/SMBus input buffer

Note 1: Default assignment for ECCP2 when Configuration bit, CCP2MX, is set.
2: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-4: PIC18F8527/8622/8627/8722 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTF is a bidirectional I/O port.
RF0/AN5	24			
RF0		I/O	ST	Digital I/O.
AN5		I	Analog	Analog input 5.
RF1/AN6/C2OUT	23			
RF1		I/O	ST	Digital I/O.
AN6		I	Analog	Analog input 6.
C2OUT		O	—	Comparator 2 output.
RF2/AN7/C1OUT	18			
RF2		I/O	ST	Digital I/O.
AN7		I	Analog	Analog input 7.
C1OUT		O	—	Comparator 1 output.
RF3/AN8	17			
RF3		I/O	ST	Digital I/O.
AN8		I	Analog	Analog input 8.
RF4/AN9	16			
RF4		I/O	ST	Digital I/O.
AN9		I	Analog	Analog input 9.
RF5/AN10/CV_{REF}	15			
RF5		I/O	ST	Digital I/O.
AN10		I	Analog	Analog input 10.
CV_{REF}		O	Analog	Comparator reference voltage output.
RF6/AN11	14			
RF6		I/O	ST	Digital I/O.
AN11		I	Analog	Analog input 11.
RF7/$\overline{SS1}$	13			
RF7		I/O	ST	Digital I/O.
$\overline{SS1}$		I	TTL	SPI slave select input.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels Analog = Analog input
I = Input O = Output
P = Power I^2C™/SMB = I^2C/SMBus input buffer

Note 1: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared (all operating modes except Microcontroller mode).
2: Default assignment for ECCP2 in all operating modes (CCP2MX is set).
3: Alternate assignment for ECCP2 when CCP2MX is cleared (Microcontroller mode only).
4: Default assignment for P1B/P1C/P3B/P3C (ECCPMX is set).
5: Alternate assignment for P1B/P1C/P3B/P3C (ECCPMX is clear).

2.0 OSCILLATOR CONFIGURATIONS

2.1 Oscillator Types

The PIC18F8722 family of devices can be operated in ten different oscillator modes. The user can program the Configuration bits, FOSC<3:0>, in Configuration Register 1H to select one of these ten modes:

1. LP Low-Power Crystal
2. XT Crystal/Resonator
3. HS High-Speed Crystal/Resonator
4. HSPLL High-Speed Crystal/Resonator with PLL enabled
5. RC External Resistor/Capacitor with FOSC/4 output on RA6
6. RCIO External Resistor/Capacitor with I/O on RA6
7. INTIO1 Internal Oscillator with FOSC/4 output on RA6 and I/O on RA7
8. INTIO2 Internal Oscillator with I/O on RA6 and RA7
9. EC External Clock with FOSC/4 output
10. ECIO External Clock with I/O on RA6

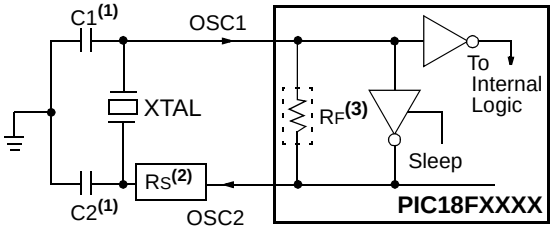
2.2 Crystal Oscillator/Ceramic Resonators

In XT, LP, HS or HSPLL Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 2-1 shows the pin connections.

The oscillator design requires the use of a parallel cut crystal.

Note:	Use of a series cut crystal may give a frequency out of the crystal manufacturer's specifications.

FIGURE 2-1: CRYSTAL/CERAMIC RESONATOR OPERATION (XT, LP, HS OR HSPLL CONFIGURATION)



Note 1: See Table 2-1 and Table 2-2 for initial values of C1 and C2.

2: A series resistor (RS) may be required for AT strip cut crystals.

3: RF varies with the oscillator mode chosen.

TABLE 2-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Typical Capacitor Values Used:			
Mode	**Freq**	**OSC1**	**OSC2**
XT	3.58 MHz	22 pF	22 pF

Capacitor values are for design guidance only.

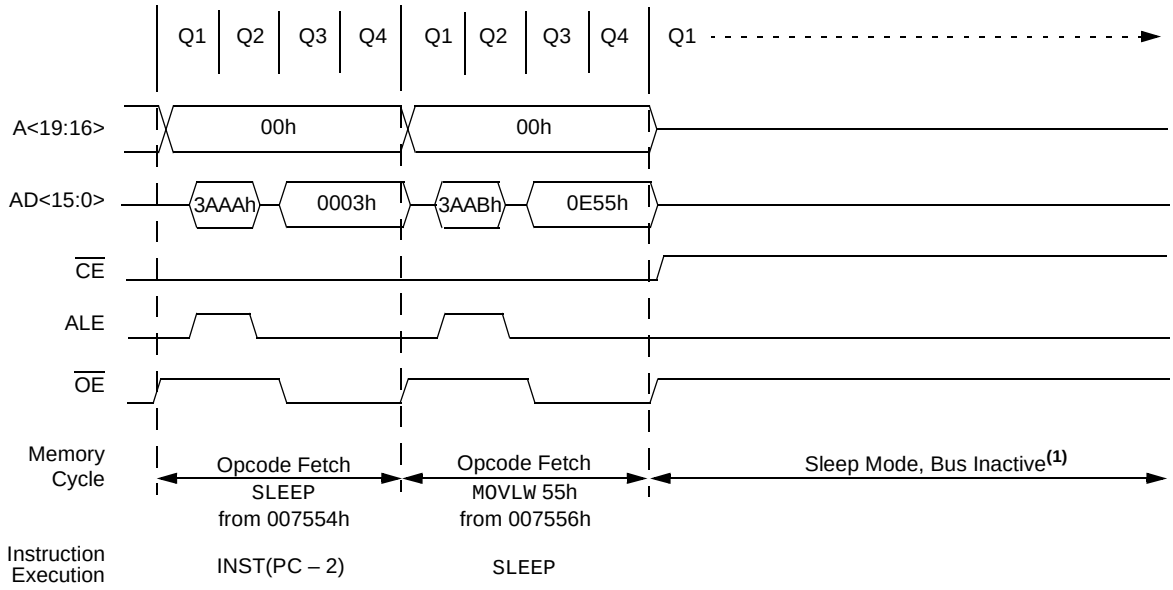
Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application. Refer to the following application notes for oscillator specific information:

- AN588 – PIC® Microcontroller Oscillator Design Guide
- AN826 – Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices
- AN849 – Basic PIC® Oscillator Design
- AN943 – Practical PIC® Oscillator Analysis and Design
- AN949 – Making Your Oscillator Work

See the notes following Table 2-2 for additional information.

Note:	When using resonators with frequencies above 3.5 MHz, the use of HS mode, rather than XT mode, is recommended. HS mode may be used at any VDD for which the controller is rated. If HS is selected, it is possible that the gain of the oscillator will overdrive the resonator. Therefore, a series resistor may be placed between the OSC2 pin and the resonator. As a good starting point, the recommended value of RS is 330Ω.

FIGURE 7-6: EXTERNAL MEMORY BUS TIMING FOR SLEEP (MICROPROCESSOR MODE)



Note 1: Bus becomes inactive regardless of power-managed mode entered when SLEEP is executed.

14.0 TIMER2 MODULE

The Timer2 timer module incorporates the following features:

- 8-bit Timer and Period registers (TMR2 and PR2, respectively)
- Readable and writable (both registers)
- Software programmable prescaler (1:1, 1:4 and 1:16)
- Software programmable postscaler (1:1 through 1:16)
- Interrupt on TMR2 to PR2 match
- Optional use as the shift clock for the MSSPx module

The module is controlled through the T2CON register (Register 14-1), which enables or disables the timer and configures the prescaler and postscaler. Timer2 can be shut off by clearing control bit, TMR2ON (T2CON<2>), to minimize power consumption.

A simplified block diagram of the module is shown in Figure 14-1.

14.1 Timer2 Operation

In normal operation, TMR2 is incremented from 00h on each clock (FOSC/4). A 4-bit counter/prescaler on the clock input gives direct input, divide-by-4 and divide-by-16 prescale options; these are selected by the prescaler control bits, T2CKPS<1:0> (T2CON<1:0>). The value of TMR2 is compared to that of the period register, PR2, on each clock cycle. When the two values match, the comparator generates a match signal as the timer output. This signal also resets the value of TMR2 to 00h on the next cycle and drives the output counter/postscaler (see **Section 14.2 "Timer2 Interrupt"**).

The TMR2 and PR2 registers are both directly readable and writable. The TMR2 register is cleared on any device Reset, while the PR2 register initializes at FFh. Both the prescaler and postscaler counters are cleared on the following events:

- a write to the TMR2 register
- a write to the T2CON register
- any device Reset (Power-on Reset, $\overline{\text{MCLR}}$ Reset, Watchdog Timer Reset or Brown-out Reset)

TMR2 is not cleared when T2CON is written.

REGISTER 14-1: T2CON: TIMER2 CONTROL REGISTER

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	T2OUTPS3	T2OUTPS2	T2OUTPS1	T2OUTPS0	TMR2ON	T2CKPS1	T2CKPS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **Unimplemented:** Read as '0'

bit 6-3 **T2OUTPS<3:0>**: Timer2 Output Postscale Select bits
0000 = 1:1 Postscale
0001 = 1:2 Postscale
•
•
•
1111 = 1:16 Postscale

bit 2 **TMR2ON**: Timer2 On bit
1 = Timer2 is on
0 = Timer2 is off

bit 1-0 **T2CKPS<1:0>**: Timer2 Clock Prescale Select bits
00 = Prescaler is 1
01 = Prescaler is 4
1x = Prescaler is 16

17.1 CCP Module Configuration

Each Capture/Compare/PWM module is associated with a control register (generically, CCPxCON) and a data register (CCPRx). The data register, in turn, is comprised of two 8-bit registers: CCPRxL (low byte) and CCPRxH (high byte). All registers are both readable and writable.

17.1.1 CCP MODULES AND TIMER RESOURCES

The CCP/ECCP modules utilize Timers 1, 2, 3 or 4, depending on the mode selected. Timer1 and Timer3 are available to modules in Capture or Compare modes, while Timer2 and Timer4 are available for modules in PWM mode.

TABLE 17-1: CCP MODE – TIMER RESOURCE

CCP Mode	Timer Resource
Capture	Timer1 or Timer3
Compare	Timer1 or Timer3
PWM	Timer2 or Timer4

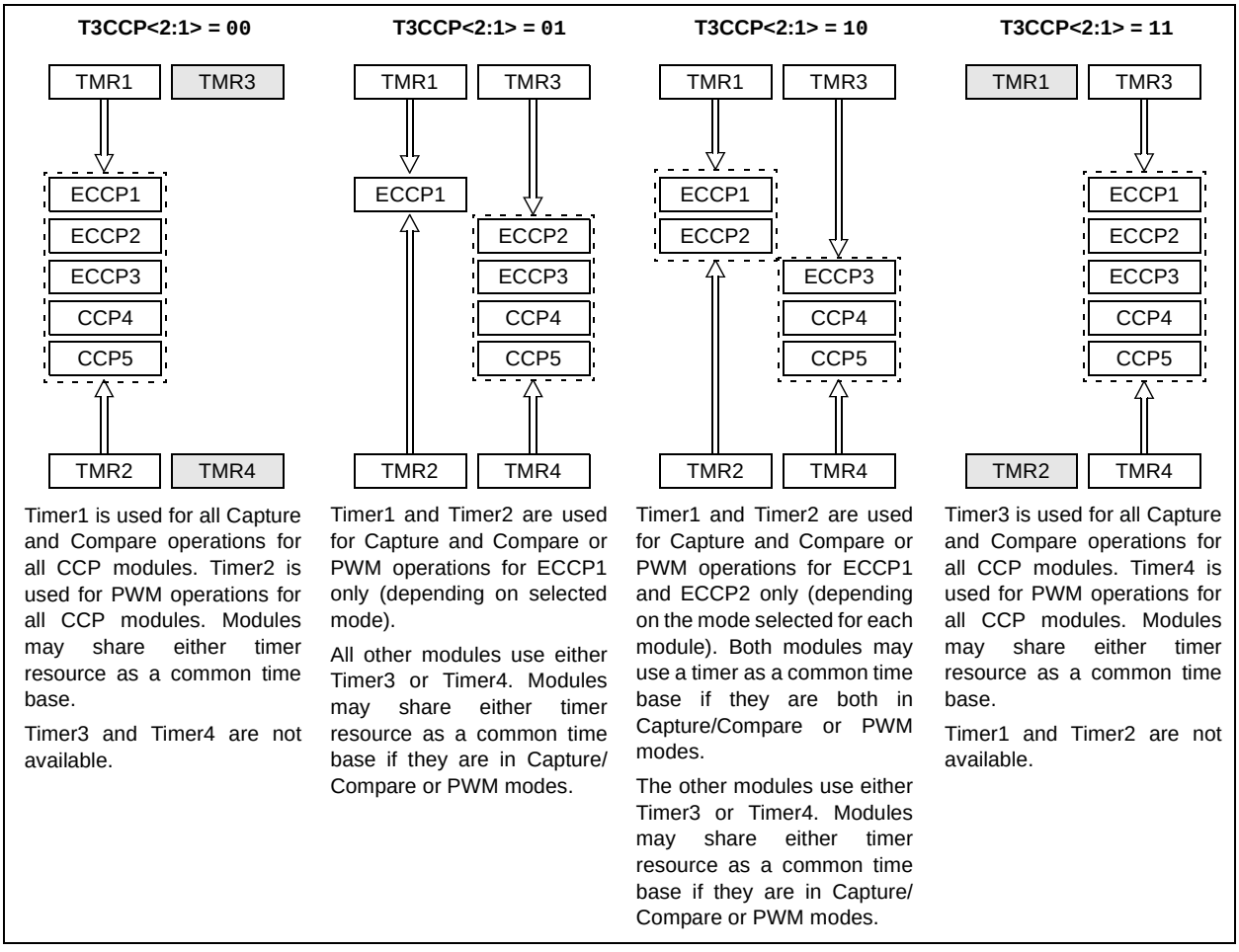
The assignment of a particular timer to a module is determined by the Timer to CCP enable bits in the T3CON register (Register 15-1). Depending on the configuration selected, up to four timers may be active at once, with modules in the same configuration (Capture/Compare or PWM) sharing timer resources. The possible configurations are shown in Figure 17-1.

17.1.2 ECCP2 PIN ASSIGNMENT

The pin assignment for ECCP2 (Capture input, Compare and PWM output) can change, based on device configuration. The CCP2MX Configuration bit determines which pin ECCP2 is multiplexed to. By default, it is assigned to RC1 (CCP2MX = 1). If the Configuration bit is cleared, ECCP2 is multiplexed with RE7 in Microcontroller mode, or RE3 in all other modes.

Changing the pin assignment of ECCP2 does not automatically change any requirements for configuring the port pin. Users must always verify that the appropriate TRIS register is configured correctly for ECCP2 operation regardless of where it is located.

FIGURE 17-1: CCP AND TIMER INTERCONNECT CONFIGURATIONS



Timer1 is used for all Capture and Compare operations for all CCP modules. Timer2 is used for PWM operations for all CCP modules. Modules may share either timer resource as a common time base.

Timer3 and Timer4 are not available.

Timer1 and Timer2 are used for Capture and Compare or PWM operations for ECCP1 only (depending on selected mode).

All other modules use either Timer3 or Timer4. Modules may share either timer resource as a common time base if they are in Capture/ Compare or PWM modes.

Timer1 and Timer2 are used for Capture and Compare or PWM operations for ECCP1 and ECCP2 only (depending on the mode selected for each module). Both modules may use a timer as a common time base if they are both in Capture/Compare or PWM modes.

The other modules use either Timer3 or Timer4. Modules may share either timer resource as a common time base if they are in Capture/ Compare or PWM modes.

Timer3 is used for all Capture and Compare operations for all CCP modules. Timer4 is used for PWM operations for all CCP modules. Modules may share either timer resource as a common time base.

Timer1 and Timer2 are not available.

FIGURE 19-8: I²C™ SLAVE MODE TIMING WITH SEN = 0 (RECEPTION, 7-BIT ADDRESS)

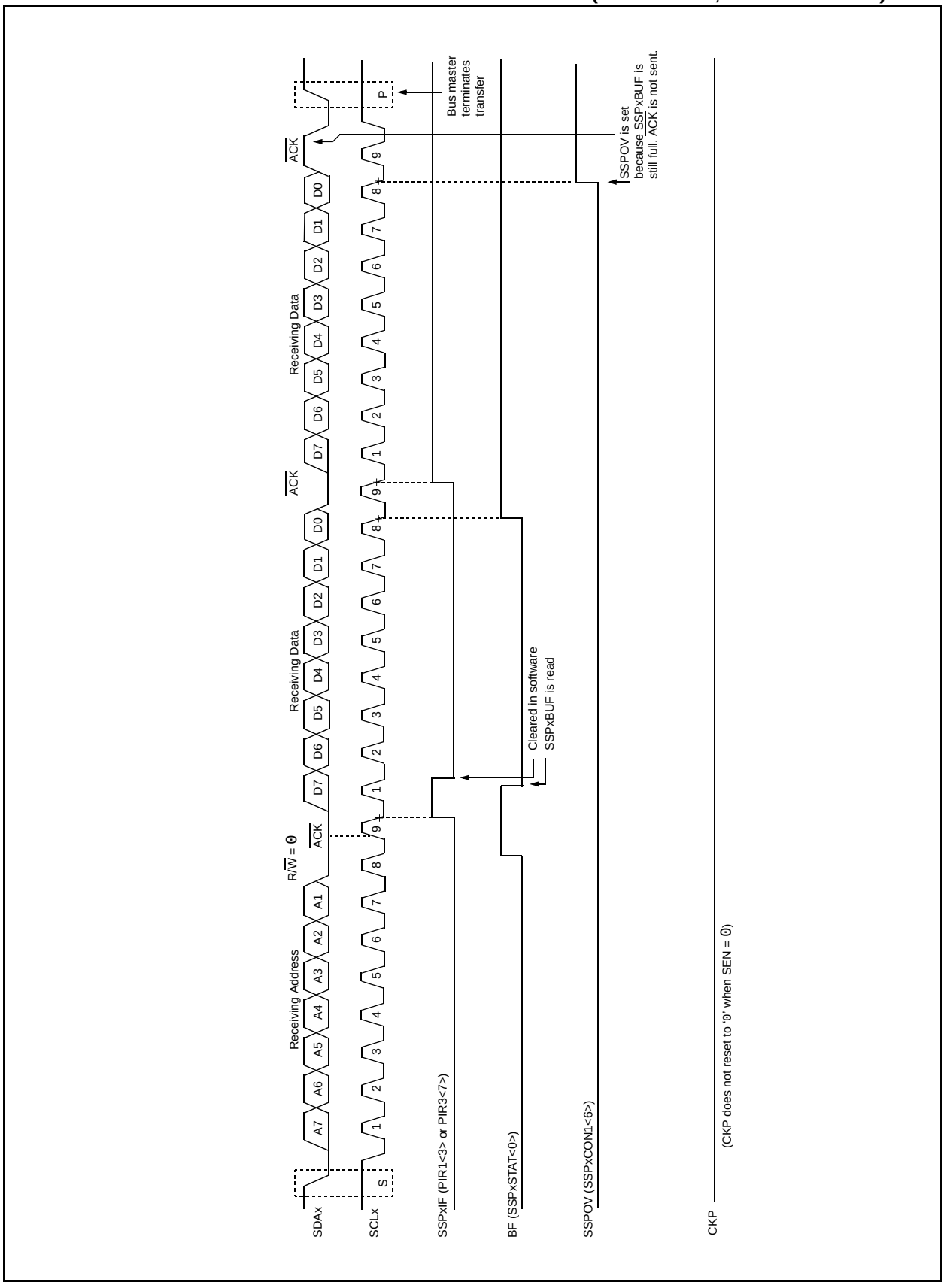
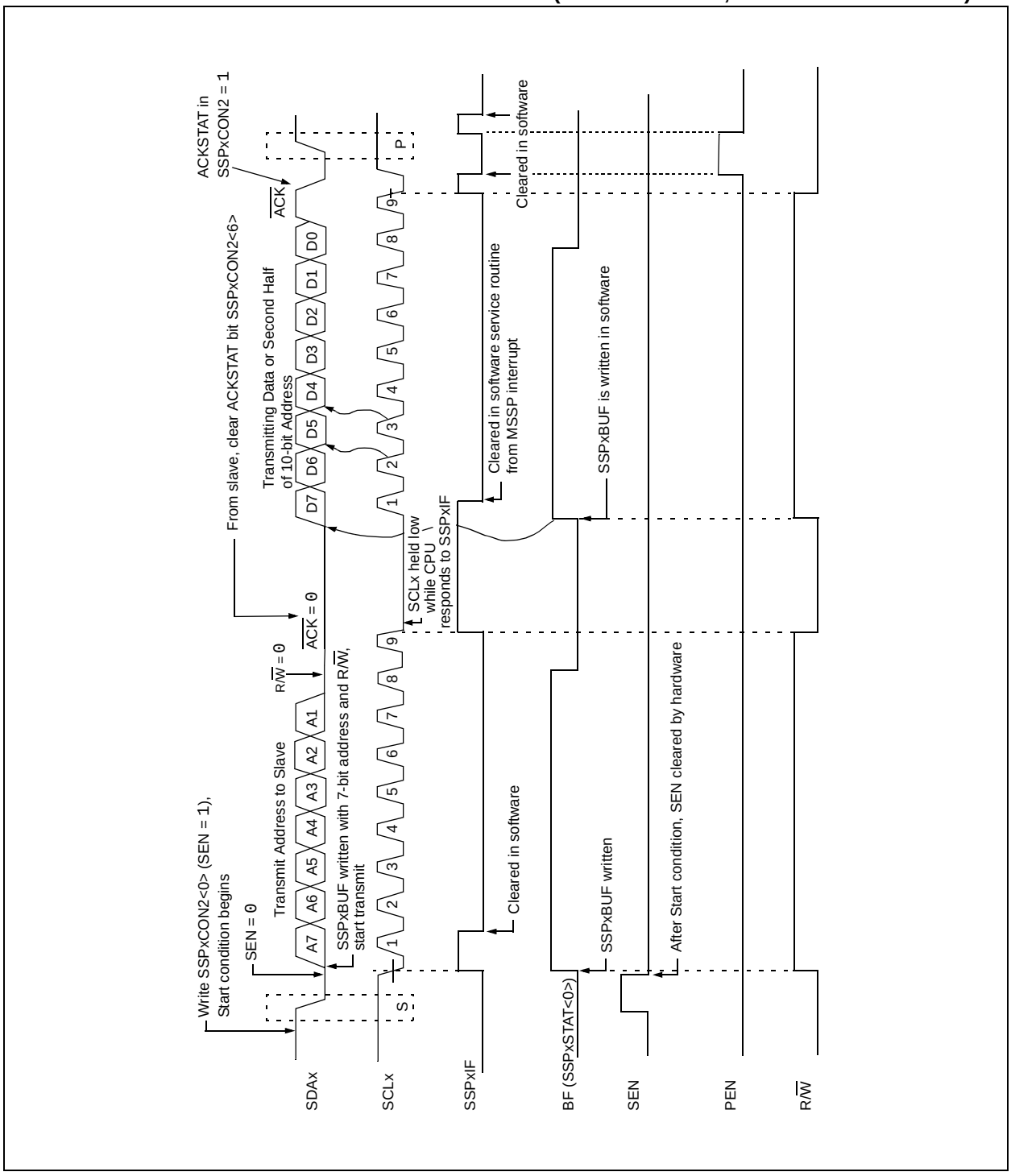


FIGURE 19-21: I²C™ MASTER MODE WAVEFORM (TRANSMISSION, 7 OR 10-BIT ADDRESS)



REGISTER 20-1: TXSTAx: TRANSMIT STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-1	R/W-0
CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **CSRC:** Clock Source Select bit

Asynchronous mode:
Don't care.

Synchronous mode:
1 = Master mode (clock generated internally from BRG)
0 = Slave mode (clock from external source)

bit 6 **TX9:** 9-bit Transmit Enable bit

1 = Selects 9-bit transmission
0 = Selects 8-bit transmission

bit 5 **TXEN:** Transmit Enable bit

1 = Transmit enabled
0 = Transmit disabled

Note: SREN/CREN overrides TXEN in Sync mode.

bit 4 **SYNC:** EUSART Mode Select bit

1 = Synchronous mode
0 = Asynchronous mode

bit 3 **SENDB:** Send Break Character bit

Asynchronous mode:
1 = Send Sync Break on next transmission (cleared by hardware upon completion)
0 = Sync Break transmission completed

Synchronous mode:
Don't care.

bit 2 **BRGH:** High Baud Rate Select bit

Asynchronous mode:
1 = High speed
0 = Low speed

Synchronous mode:
Unused in this mode.

bit 1 **TRMT:** Transmit Shift Register Status bit

1 = TSRx empty
0 = TSRx full

bit 0 **TX9D:** Ninth bit of Transmit Data

Can be address/data bit or a parity bit.

TABLE 20-3: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 0											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	—	—	—	—	—	—
1.2	—	—	—	1.221	1.73	255	1.202	0.16	129	1.201	-0.16	103
2.4	2.441	1.73	255	2.404	0.16	129	2.404	0.16	64	2.403	-0.16	51
9.6	9.615	0.16	64	9.766	1.73	31	9.766	1.73	15	9.615	-0.16	12
19.2	19.531	1.73	31	19.531	1.73	15	19.531	1.73	7	—	—	—
57.6	56.818	-1.36	10	62.500	8.51	4	52.083	-9.58	2	—	—	—
115.2	125.000	8.51	4	104.167	-9.58	2	78.125	-32.18	1	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 0								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.16	207	0.300	-0.16	103	0.300	-0.16	51
1.2	1.202	0.16	51	1.201	-0.16	25	1.201	-0.16	12
2.4	2.404	0.16	25	2.403	-0.16	12	—	—	—
9.6	8.929	-6.99	6	—	—	—	—	—	—
19.2	20.833	8.51	2	—	—	—	—	—	—
57.6	62.500	8.51	0	—	—	—	—	—	—
115.2	62.500	-45.75	0	—	—	—	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 0											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	—	—	—	—	—	—
1.2	—	—	—	—	—	—	—	—	—	—	—	—
2.4	—	—	—	—	—	—	2.441	1.73	255	2.403	-0.16	207
9.6	9.766	1.73	255	9.615	0.16	129	9.615	0.16	64	9.615	-0.16	51
19.2	19.231	0.16	129	19.231	0.16	64	19.531	1.73	31	19.230	-0.16	25
57.6	58.140	0.94	42	56.818	-1.36	21	56.818	-1.36	10	55.555	3.55	8
115.2	113.636	-1.36	21	113.636	-1.36	10	125.000	8.51	4	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 0								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	0.300	-0.16	207
1.2	1.202	0.16	207	1.201	-0.16	103	1.201	-0.16	51
2.4	2.404	0.16	103	2.403	-0.16	51	2.403	-0.16	25
9.6	9.615	0.16	25	9.615	-0.16	12	—	—	—
19.2	19.231	0.16	12	—	—	—	—	—	—
57.6	62.500	8.51	3	—	—	—	—	—	—
115.2	125.000	8.51	1	—	—	—	—	—	—

REGISTER 25-4: CONFIG3L: CONFIGURATION REGISTER 3 LOW (BYTE ADDRESS 300004h)(1)

R/P-1	R/P-1	R/P-1	R/P-1	U-0	U-0	R/P-1	R/P-1
WAIT	BW	ABW1	ABW0	—	—	PM1	PM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **WAIT:** External Bus Data Wait Enable bit
1 = Wait selections are unavailable for table reads and table writes
0 = Wait selections for table reads and table writes are determined by the WAIT<1:0> bits

bit 6 **BW:** Data Bus Width Select bit
1 = 16-bit External Bus mode
0 = 8-bit External Bus mode

bit 5-4 **ABW<1:0>:** Address Bus Width Select bits
11 = 20-bit address bus
10 = 16-bit address bus
01 = 12-bit address bus
00 = 8-bit address bus

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **PM<1:0>:** Processor Data Memory Mode Select bits
11 = Microcontroller mode
10 = Microprocessor mode
01 = Microprocessor with Boot Block mode
00 = Extended Microcontroller mode

Note 1: This register is unimplemented in PIC18F6527/6622/6627/6722 devices.

MOVFF **Move f to f**

Syntax: MOVFF f_s,f_d

Operands: $0 \le f_s \le 4095$
$0 \le f_d \le 4095$

Operation: $(f_s) \rightarrow f_d$

Status Affected: None

Encoding:

1st word (source)	1100	ffff	ffff	ffffs
2nd word (destin.)	1111	ffff	ffff	ffffd

Description: The contents of source register 'f_s' are moved to destination register 'f_d'. Location of source 'f_s' can be anywhere in the 4096-byte data space (000h to FFFh) and location of destination 'f_d' can also be anywhere from 000h to FFFh.

Either source or destination can be W (a useful special situation).

MOVFF is particularly useful for transferring a data memory location to a peripheral register (such as the transmit buffer or an I/O port).

The MOVFF instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register

Words: 2

Cycles: 2 (3)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f' (src)	Process Data	No operation
Decode	No operation No dummy read	No operation	Write register 'f' (dest)

Example: MOVFF REG1, REG2

Before Instruction
REG1 = 33h
REG2 = 11h
After Instruction
REG1 = 33h
REG2 = 33h

MOVLB **Move Literal to Low Nibble in BSR**

Syntax: MOVLW k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow BSR$

Status Affected: None

Encoding:

0000	0001	kkkk	kkkk

Description: The eight-bit literal 'k' is loaded into the Bank Select Register (BSR). The value of BSR<7:4> always remains '0' regardless of the value of k_7:k_4.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write literal 'k' to BSR

Example: MOVLB 5

Before Instruction
BSR Register = 02h
After Instruction
BSR Register = 05h

RLNCF **Rotate Left f (no carry)**

Syntax: RLNCF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f<n>) → dest<n + 1>,
(f<7>) → dest<0>

Status Affected: N, Z

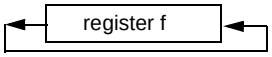
Encoding:

0100	01da	ffff	ffff

Description: The contents of register ‘f’ are rotated one bit to the left. If ‘d’ is ‘0’, the result is placed in W. If ‘d’ is ‘1’, the result is stored back in register ‘f’ (default).

If ‘a’ is ‘0’, the Access Bank is selected. If ‘a’ is ‘1’, the BSR is used to select the GPR bank (default).

If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 26.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

Example: RLNCF REG, 1, 0

Before Instruction
REG = 1010 1011
After Instruction
REG = 0101 0111

RRCF **Rotate Right f through Carry**

Syntax: RRCF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f<n>) → dest<n – 1>,
(f<0>) → C,
(C) → dest<7>

Status Affected: C, N, Z

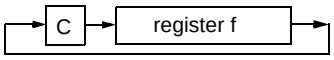
Encoding:

0011	00da	ffff	ffff

Description: The contents of register ‘f’ are rotated one bit to the right through the Carry flag. If ‘d’ is ‘0’, the result is placed in W. If ‘d’ is ‘1’, the result is placed back in register ‘f’ (default).

If ‘a’ is ‘0’, the Access Bank is selected. If ‘a’ is ‘1’, the BSR is used to select the GPR bank (default).

If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 26.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

Example: RRCF REG, 0, 0

Before Instruction
REG = 1110 0110
C = 0
After Instruction
REG = 1110 0110
W = 0111 0011
C = 0

28.1 DC Characteristics: Supply Voltage PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended) PIC18LF6X27/6X22/8X27/8X22 (Industrial)

PIC18LF6X27/6X22/8X27/8X22 (Industrial)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
D001	VDD	**Supply Voltage**					
		PIC18LF6X27/6X22/8X27/8X22	2.0	—	5.5	V	
		PIC18F6X27/6X22/8X27/8X22	4.2	—	5.5	V	
D002	VDR	**RAM Data Retention Voltage(1)**	1.5	—	—	V	
D003	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	0.7	V	See **Section 4.3 "Power-on Reset (POR)"** for details
D004	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	See **Section 4.3 "Power-on Reset (POR)"** for details
D005	VBOR	**Brown-out Reset Voltage**					
		BORV<1:0> = 11	2.00	2.05	2.16	V	PIC18LF6627/6722/8627/8722
		BORV<1:0> = 11	2.00	2.11	2.22	V	PIC18LF6527/6622/8527/8622
		BORV<1:0> = 10	2.65	2.79	2.93	V	PIC18LF6X27/6X22/8X27/8X22
		BORV<1:0> = 01(2)	4.11	4.33	4.55	V	All devices
		BORV<1:0> = 00	4.36	4.59	4.82	V	All devices

Legend: Shading of rows is to assist in readability of the table.

Note 1: This is the limit to which VDD can be lowered in Sleep mode, or during a device Reset, without losing RAM data.

2: With BOR enabled, full-speed operation (FOSC = 40 MHz) is supported until a BOR occurs. The VDD may be below the minimum voltage for this frequency.

28.2 DC Characteristics: Power-Down and Supply Current PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended) PIC18LF6X27/6X22/8X27/8X22 (Industrial) (Continued)

PIC18LF6X27/6X22/8X27/8X22 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2)						
	PIC18LF6X27/6X22/8X27/8X22	1.0	1.3	mA	-40°C	VDD = 2.0V	FOSC = 4 MHz (**RC_RUN** mode, Internal oscillator source)
		1.0	1.3	mA	+25°C		
		1.0	1.3	mA	+85°C		
	PIC18LF6X27/6X22/8X27/8X22	1.6	1.9	mA	-40°C	VDD = 3.0V	
		1.6	1.9	mA	+25°C		
		1.6	1.9	mA	+85°C		
	All devices	3.0	3.5	mA	-40°C	VDD = 5.0V	
		3.0	3.4	mA	+25°C		
		3.0	3.4	mA	+85°C		
	Extended devices only	3.0	3.4	mA	+125°C		
	PIC18LF6X27/6X22/8X27/8X22	3.5	5	µA	-40°C	VDD = 2.0V	FOSC = 31 kHz (**RC_IDLE** mode, Internal oscillator source)
		3.7	5	µA	+25°C		
		4.3	9.5	µA	+85°C		
	PIC18LF6X27/6X22/8X27/8X22	5.4	7	µA	-40°C	VDD = 3.0V	
		5.7	8	µA	+25°C		
		7.0	15	µA	+85°C		
	All devices	11	15	µA	-40°C	VDD = 5.0V	
		11.8	15	µA	+25°C		
		13.5	35	µA	+85°C		
	Extended devices only	25	200	µA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD OR VSS;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

28.2 DC Characteristics: Power-Down and Supply Current PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended) PIC18LF6X27/6X22/8X27/8X22 (Industrial) (Continued)

PIC18LF6X27/6X22/8X27/8X22 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2)						
	All devices	9.0	13	mA	-40°C	VDD = 4.2V	FOSC = 4 MHz, 16 MHz internal (**PRI_RUN HS+PLL**)
		9.0	13	mA	+25°C		
		9.0	13	mA	+85°C		
	Extended devices only	9.6	15	mA	+125°C		
	All devices	12	15	mA	-40°C	VDD = 5.0V	FOSC = 4 MHz, 16 MHz internal (**PRI_RUN HS+PLL**)
		12	15	mA	+25°C		
		12	15	mA	+85°C		
	Extended devices only	12	17	mA	+125°C		
	All devices	18	23.5	mA	-40°C	VDD = 4.2V	FOSC = 10 MHz, 40 MHz internal (**PRI_RUN HS+PLL**)
		19	23.5	mA	+25°C		
		19	23.5	mA	+85°C		
	All devices	25	29	mA	-40°C	VDD = 5.0V	FOSC = 10 MHz, 40 MHz internal (**PRI_RUN HS+PLL**)
		25	29	mA	+25°C		
		25	29	mA	+85°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD OR VSS;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

28.2 DC Characteristics: Power-Down and Supply Current PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended) PIC18LF6X27/6X22/8X27/8X22 (Industrial) (Continued)

PIC18LF6X27/6X22/8X27/8X22 (Industrial)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended)	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Device	Typ	Max	Units	Conditions		
D026 (ΔIAD)	**A/D Converter**	0.2	1	μA	-40°C to +85°C	VDD = 2.0V	A/D on, not converting, Sleep mode
		0.2	1	μA	-40°C to +85°C	VDD = 3.0V	
		0.2	1	μA	-40°C to +85°C	VDD = 5.0V	
		0.5	4	μA	-40°C to +125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD OR VSS;
MCLR = VDD; WDT enabled/disabled as specified.

3: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

28.4.2 TIMING CONDITIONS

The temperature and voltages specified in Table 28-5 apply to all timing specifications unless otherwise noted. Figure 28-5 specifies the load conditions for the timing specifications.

Note: Because of space limitations, the generic terms "PIC18FXXXX" and "PIC18LFXXXX" are used throughout this section to refer to the PIC18F6X27/6X22/8X27/8X22 and PIC18LF6X27/6X22/8X27/8X22 families of devices specifically and only those devices.

TABLE 28-5: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range as described in the DC specifications in **Section 28.1** and **Section 28.3**. LF parts operate for industrial temperatures only.

FIGURE 28-5: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

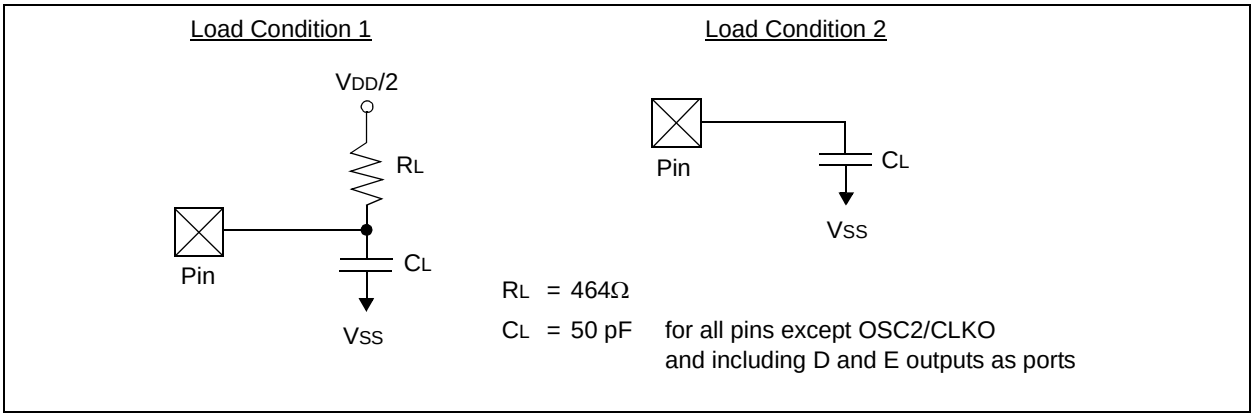


TABLE 28-7: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 4.2V TO 5.5V)

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
F10	FOSC	Oscillator Frequency Range	4	—	10	MHz	HS mode only
F11	FSYS	On-Chip VCO System Frequency	16	—	40	MHz	HS mode only
F12	t_{rc}	PLL Start-up Time (Lock Time)	—	—	2	ms	
F13	ΔCLK	CLKO Stability (Jitter)	-2	—	+2	%	

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 28-8: AC CHARACTERISTICS: INTERNAL RC ACCURACY PIC18F6X27/6X22/8X27/8X22 (INDUSTRIAL, EXTENDED) PIC18LF6X27/6X22/8X27/8X22 (INDUSTRIAL)

PIC18LF6X27/6X22/8X27/8X22 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	INTOSC Accuracy @ Freq = 8 MHz, 4 MHz, 2 MHz, 1 MHz, 500 kHz, 250 kHz, 125 kHz(1)						
	PIC18LF6X27/6X22/8X27/8X22	-2	+/-1	2	%	+25°C	VDD = 2.7-3.3V
		-5	+/-1	5	%	-40°C to +85°C	VDD = 2.7-3.3V
	PIC18F6X27/6X22/8X27/8X22	-2	+/-1	2	%	+25°C	VDD = 4.5-5.5V
		-5	+/-1	5	%	-40°C to +85°C	VDD = 4.5-5.5V
	INTRC Accuracy @ Freq = 31 kHz						
	PIC18LF6X27/6X22/8X27/8X22	26.562	—	35.938	kHz	-40°C to +85°C	VDD = 2.7-3.3V
	PIC18F6X27/6X22/8X27/8X22	26.562	+/-8	35.938	kHz	-40°C to +85°C	VDD = 4.5-5.5V

Legend: Shading of rows is to assist in readability of the table.

Note 1: Frequency calibrated at 25°C. OSCTUNE register can be used to compensate for temperature drift.

NOTES: